

TLP741G

Office Machine  
Household Use Equipment  
Solid State Relay  
Switching Power Supply

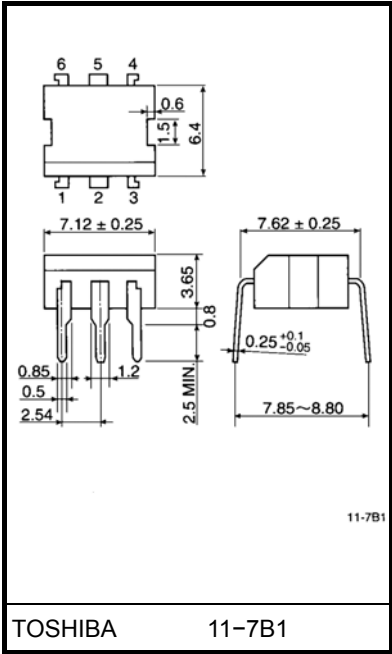
The TOSHIBA TLP741G consists of a photo-thyristor optically coupled to a gallium arsenide infrared emitting diode in a six lead plastic DIP package.

- Peak off-state voltage: 400V(min.)
- Trigger LED current: 10mA(max.)
- On-state current: 150mA(max.)
- UL recognized: UL1577, file no. E67349
- BSI approved: BS EN60065: 2002  
Certificate no. 8877  
BS EN60950-1: 2002  
Certificate no. 8878
- Isolation voltage: 4000V<sub>rms</sub>(min.)
- Option (D4) type  
VDE approved: DIN EN 60747-5-2  
Certificate no. 40009302  
Maximum operating insulation voltage: 630V<sub>PK</sub>  
Highest permissible over voltage: 6000V<sub>PK</sub>

(Note) When a EN 60747-5-2 approved type is needed,  
please designate the "option (D4)"

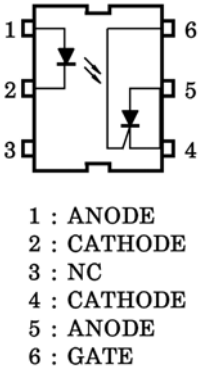
	7.62mm pich standard type	10.16mm pich (LF2) type
• Creepage distance:	7.0mm(min.)	8.0mm(min.)
Clearance:	7.0mm(min.)	8.0mm(min.)
Insulation thickness:	0.5mm(min.)	0.5mm(min.)

Unit in mm



Weight: 0.35 g (typ.)

Pin Configuration (top view)



## Absolute Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rating	Unit
LED	Forward current	I <sub>F</sub>	60	mA
	Forward current derating (Ta ≥ 39°C)	ΔI <sub>F</sub> / °C	−0.7	mA / °C
	Peak forward current (100μs pulse, 100pps)	I <sub>FP</sub>	1	A
	Power dissipation	P <sub>D</sub>	100	mW
	Power dissipation derating (Ta ≥ 25°C)	ΔP <sub>D</sub> / °C	−1.0	mW / °C
	Reverse voltage	V <sub>R</sub>	5	V
	Junction temperature	T <sub>j</sub>	125	°C
Detector	Peak forward voltage(R <sub>GK</sub> = 27kΩ)	V <sub>DRM</sub>	400	V
	Peak reverse voltage(R <sub>GK</sub> = 27kΩ)	V <sub>RRM</sub>	400	V
	On-state current	I <sub>T(RMS)</sub>	150	mA
	On-state current derating (Ta ≥ 25°C)	ΔI <sub>T</sub> / °C	−2.0	mA / °C
	Peak on-state current (100μs pulse, 120pps)	I <sub>TP</sub>	3	A
	Peak one cycle surge current	I <sub>TSM</sub>	2	A
	Peak reverse gate voltage	V <sub>GM</sub>	5	V
	Power dissipation	P <sub>D</sub>	150	mW
	Power dissipation derating (Ta ≥ 25°C)	ΔP <sub>D</sub> / °C	−2.0	mW / °C
	Junction temperature	T <sub>j</sub>	100	°C
Storage temperature range		T <sub>stg</sub>	−55~125	°C
Operating temperature range		T <sub>opr</sub>	−55~100	°C
Lead soldering temperature (10s)		T <sub>sol</sub>	260	°C
Total package power dissipation		P <sub>T</sub>	250	mW
Total package power dissipation derating (Ta ≥ 25°C)		ΔP <sub>T</sub> / °C	−3.3	mW / °C
Isolation voltage (AC, 1 min., R.H. ≤ 60%)		BV <sub>S</sub>	4000	V <sub>rms</sub>

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

## Recommended Operating Conditions

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Supply voltage	V <sub>AC</sub>	—	—	120	V <sub>ac</sub>
Forward current	I <sub>F</sub>	15	20	25	mA
Operating temperature	T <sub>opr</sub>	−25	—	85	°C
Gate to cathode resistance	R <sub>GK</sub>	—	27	33	kΩ
Gate to cathode capacity	C <sub>GK</sub>	—	0.01	0.1	μF

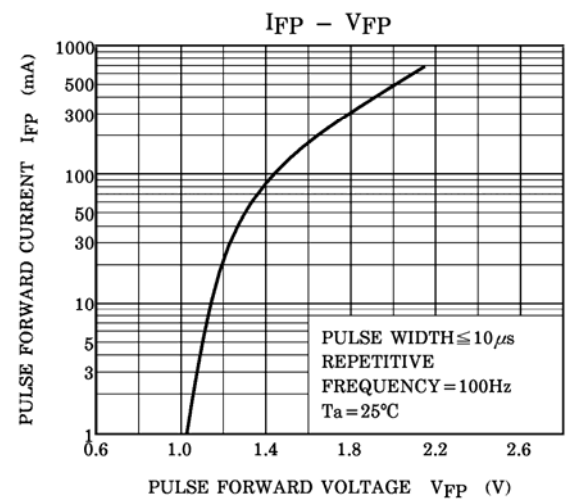
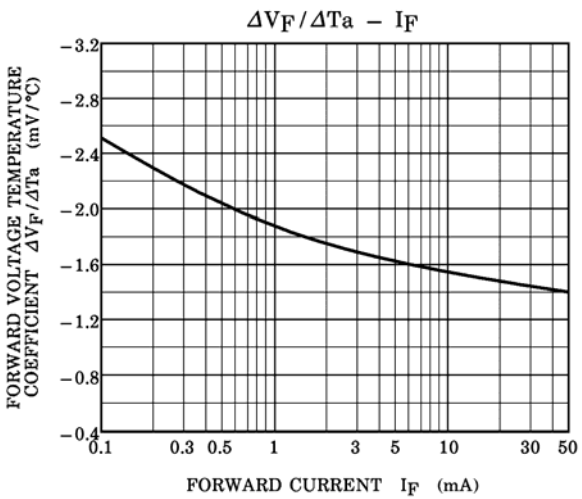
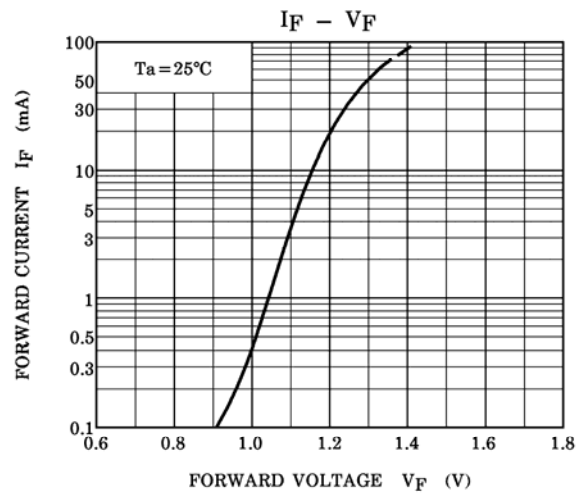
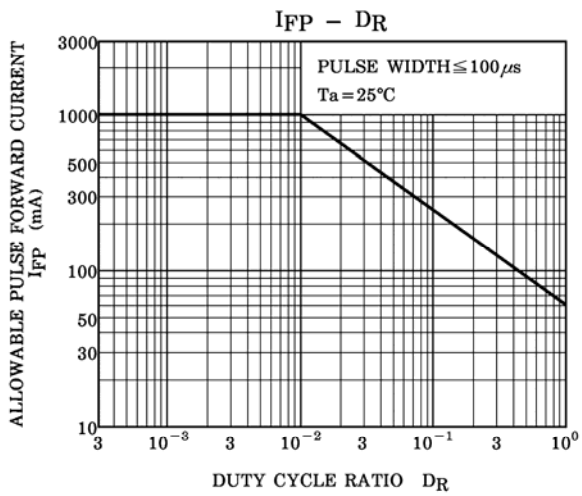
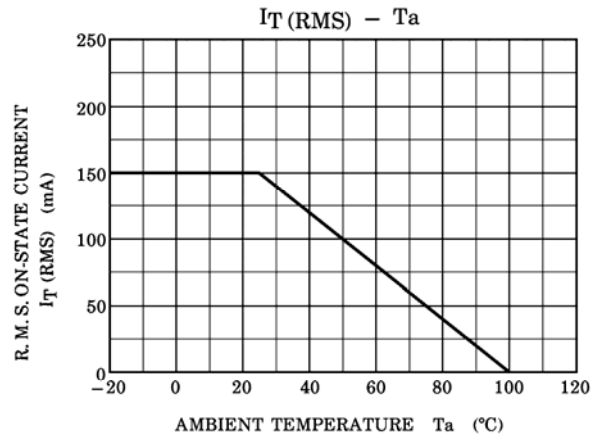
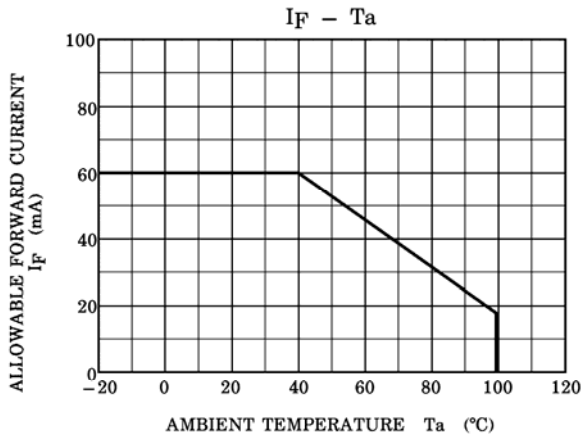
Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

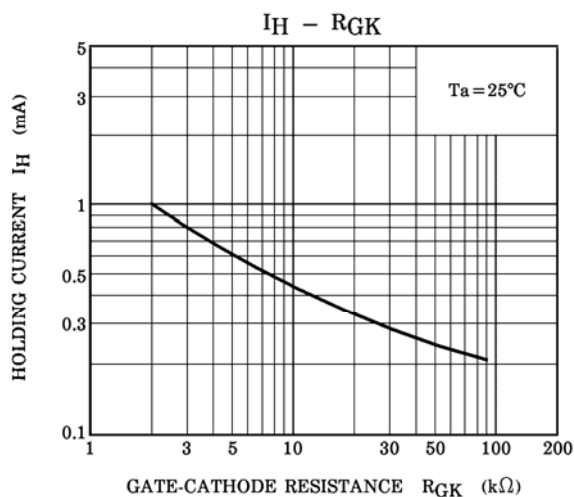
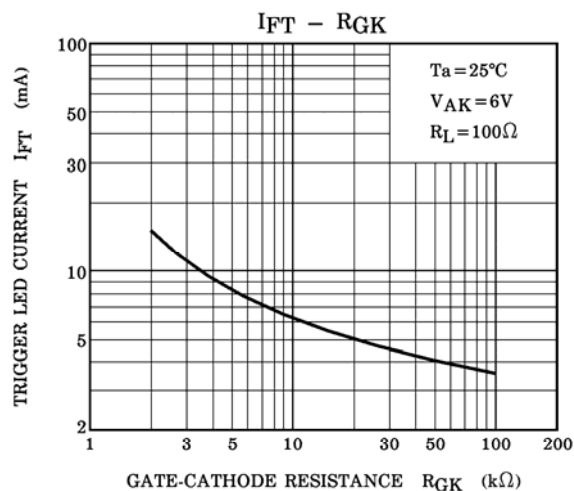
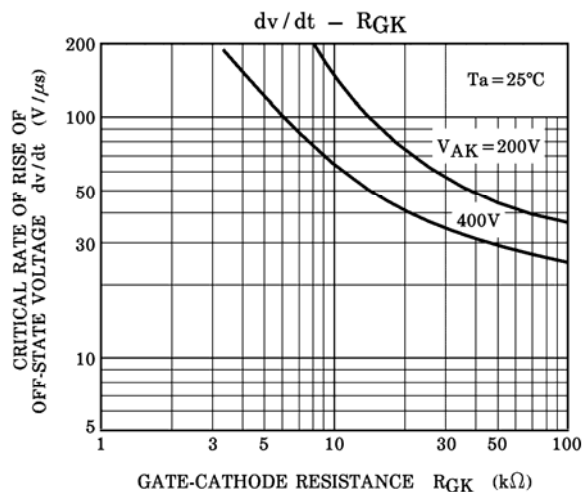
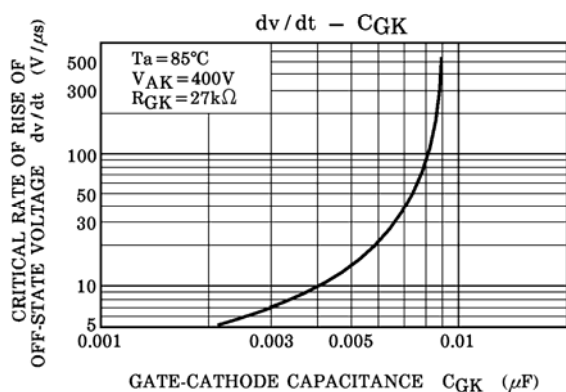
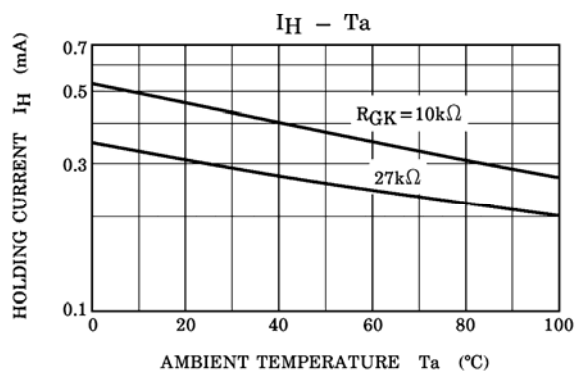
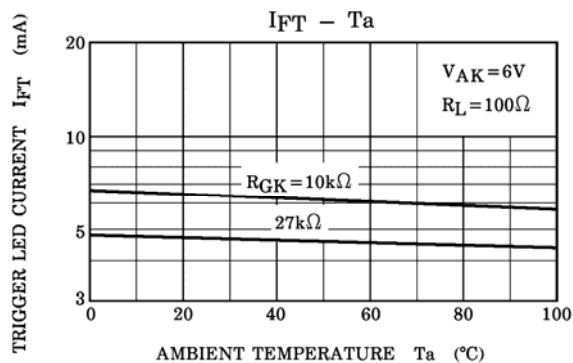
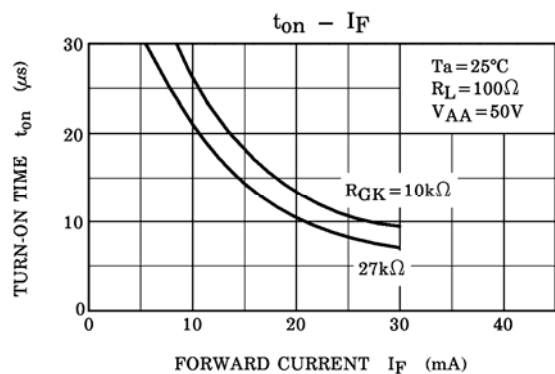
## Individual Electrical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition		Min.	Typ.	Max.	Unit
LED	Forward voltage	$V_F$	$I_F = 10\text{mA}$		1.0	1.15	1.3	V
	Reverse current	$I_R$	$V_R = 5\text{V}$		—	—	10	$\mu\text{A}$
	Capacitance	$C_T$	$V = 0, f = 1\text{MHz}$		—	30	—	pF
Detector	Off-state current	$I_{\text{DRM}}$	$V_{AK} = 400\text{V}$ $R_{GK} = 27\text{k}\Omega$	Ta = 25°C	—	10	5000	nA
				Ta = 100°C	—	1	100	$\mu\text{A}$
	Reverse current	$I_{\text{RRM}}$	$V_{KA} = 400\text{V}$ $R_{GK} = 27\text{k}\Omega$	Ta = 25°C	—	10	5000	nA
				Ta = 100°C	—	1	100	$\mu\text{A}$
	On-state voltage	$V_{\text{TM}}$	$I_{\text{TM}} = 100\text{mA}$		—	0.9	1.3	V
	Holding current	$I_H$	$R_{GK} = 27\text{k}\Omega$		—	0.2	—	mA
	Off-state dv / dt	dv/dt	$V_D = 280\text{V}, R_{GK} = 27\text{k}\Omega$		5	10	—	V/ $\mu\text{s}$
	Capacitance	$C_j$	$V = 0, f = 1\text{MHz}$	Anode to gate	—	20	—	pF
				Gate to cathode	—	350	—	

## Coupled Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Trigger LED current	$I_{\text{FT}}$	$V_{AK} = 6\text{V}, R_{GK} = 27\text{k}\Omega$	—	4	10	mA
Turn-on time	$t_{\text{ON}}$	$I_F = 30\text{mA}, V_{AA} = 50\text{V}, R_{GK} = 27\text{k}\Omega$	—	10	—	$\mu\text{s}$
Coupled dv/dt	dv/dt	$V_S = 500\text{V}, R_{GK} = 27\text{k}\Omega$	500	—	—	V/ $\mu\text{s}$
Capacitance (input to output)	$C_S$	$V_S = 0, f = 1\text{MHz}$	—	0.8	—	pF
Isolation resistance	$R_S$	$V_S = 500\text{V}$	$1 \times 10^{12}$	$10^{14}$	—	$\Omega$
Isolation voltage	$BV_S$	AC, 1 minute	4000	—	—	$V_{\text{rms}}$
		AC, 1 second, in oil	—	10000	—	
		DC, 1 minute, in oil	—	10000	—	$V_{\text{dc}}$





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